



Product Change Notification

Change Notification #: 117531 - 01
Change Title: Select Arria and Stratix FPGA Products, PCN 117531-01, Product Discontinuance, End of Life
Reason for Revision: Scope in description updated
Date of Publication: June 17, 2020

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Last Product Discontinuance Order Date:	September 30, 2020
Orders are Non-Cancelable and Non-Returnable After:	September 30, 2020
Last Product Discontinuance Shipment Date:	March 30, 2021

Description of Change to the Customer:

Reason for Revision: Scope in description has been updated. This is the same revision described in PDN2007 issued on June 12, 2020.

Intel is discontinuing part numbers that currently use leaded solder bumps on the 1st level interconnect for the following Field Programmable Gate Array (FPGA) Flip Chip product families:

- Arria II GZ
- Arria V (FPGA & SoC)
- Stratix III
- Stratix IV
- Stratix V

Reason for Change:

This discontinuance notice is a follow up to advisory ADV1828 issued in January 2019.

ADV1828 informed customers of the plans related to the EU Restriction of Hazardous Substances (RoHS) Directive Exemption 15 scope change.

ADV1828 link: <https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/adv1828.pdf>

Customer Impact of Change and Recommended Action:

Customers are advised to migrate to part numbers compliant to the EU RoHS Directive (designated with a "G" suffix see Note 1) or perform a last time buy on non-compliant products (designated with a "N" suffix) impacted by this discontinuance notice.

Note 1:

The "G" suffix part numbers use the same silicon, product specifications, and are generally form, fit and function equivalent to the "N" suffix part numbers.
Stratix III has changes to the package. Please refer to the notes section in the list of affected products.

Products Affected / Intel Ordering Codes:

The list of affected Ordering Part Numbers (OPNs) can be downloaded here:

<https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/pdn2007-opn-list.xlsx>

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 1, 2020	00	Originally Published PCN
June 17, 2020	01	Scope in description updated



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117531 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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